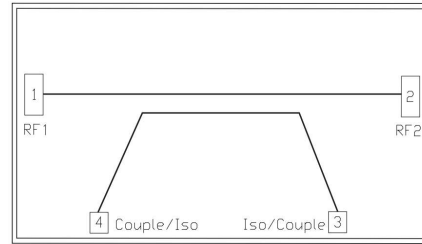


Performance

- Frequency: 2~6GHz
- Coupling: 15dB
- Coupling Flatness: 3dB
- Chip size: 4.0*1.3*0.1mm

Function Diagram

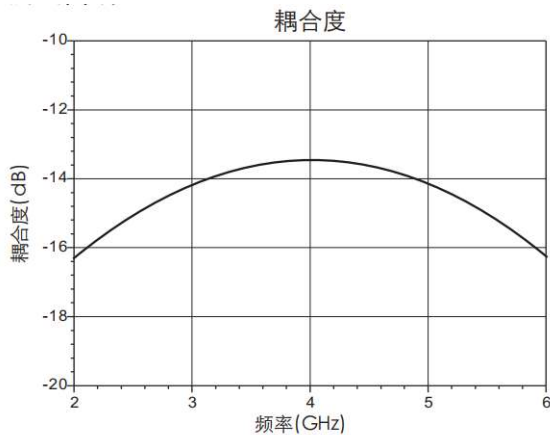


Electrical Specifications (Ta=+25°C, 50Ω system)

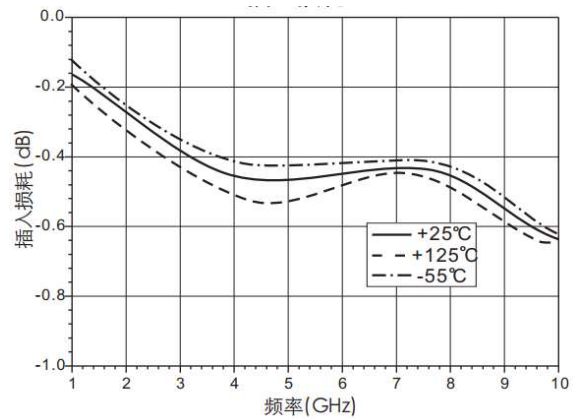
Parameter	Min	Typical	Max	Unit
Frequency Range	2~6			GHz
Coupling	13.5	15	16.5	
Insertion Loss	0.2	0.4	0.6	dB
Input Return loss	-25	-23	-22	dB
Thru Output Return loss	-34	-32	-30	dB
Coupling Output Return loss	-26	-24	-22	dB

Test Curves (Die chip + Bonding line test)

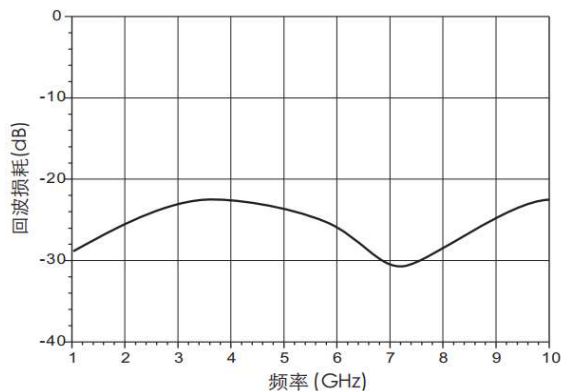
Coupling vs. Freq



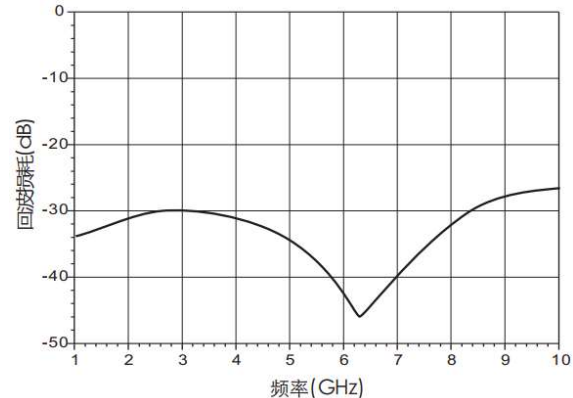
Insertion loss vs. Freq

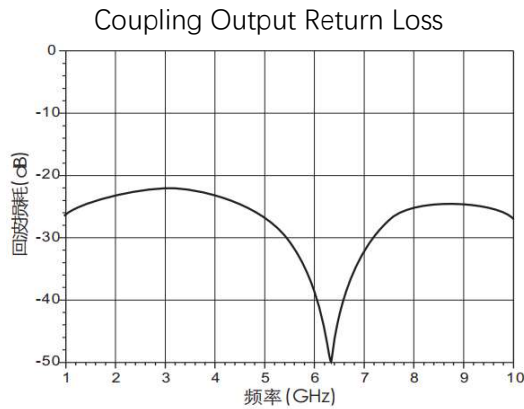


Input Return Loss vs. Freq



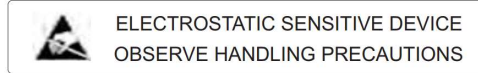
Thru output Return loss vs. Freq



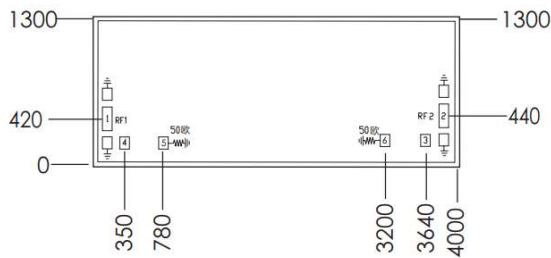


Absolute Rating

Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C
Max Input Power	10W
Static Protection (HBM)	Class 1A



Outline Size



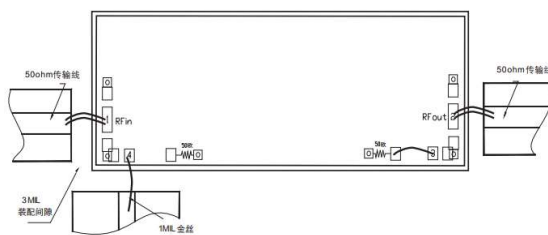
Note:

1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated, Pad size: $200 \times 100(\mu\text{m})$, $100 \times 100(\mu\text{m})$
5. Don't bonding on thru holds
6. Tolerance: $\pm 50\mu\text{m}$

Bonding Pads Definition

Number	Symbol	Description
1	RFin	RF input port, 50ohm
2	RFout	RF output port, 50 ohm
3,4	Couple/ISO	Choose either one as couple output port, another port connect to 50Ω resistor pad
5,6	LOAD	50ohm resistor pads

Application (Chip left side couple output)



Application (Chip right side couple output)

